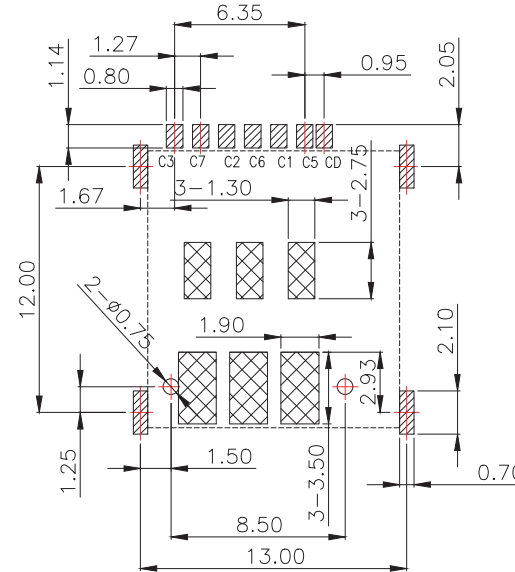
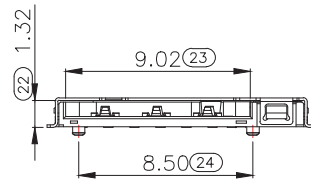
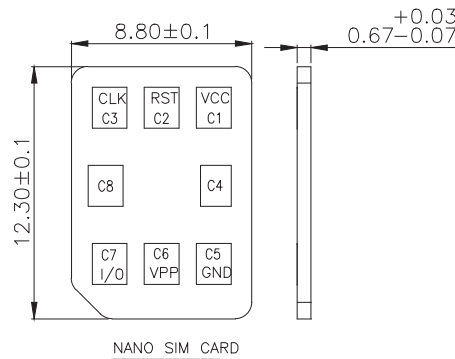
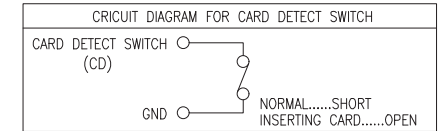


- NOTES:
- MATERIAL:
HOUSING: HI-TEMP. PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
 - PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
 - SPECIALTY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 50mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260±0/-5°C, 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature -40°C ~ +85°C;
Humidity 80% R.H MAX



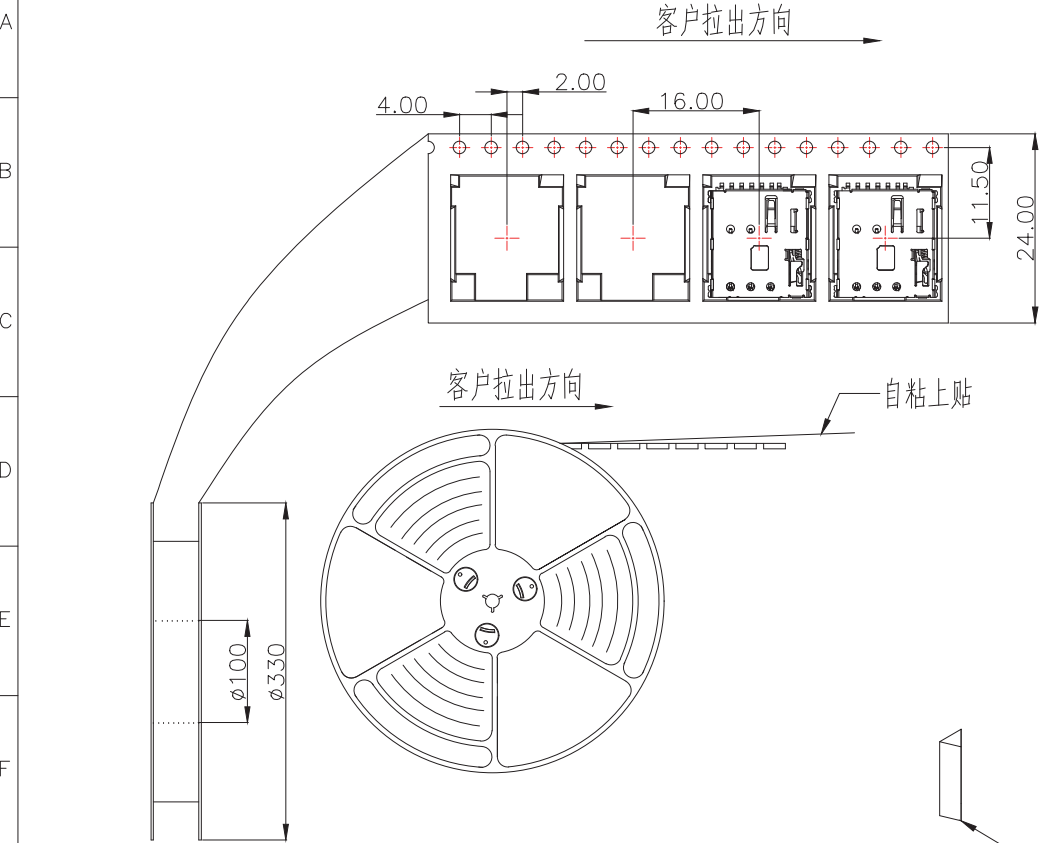
SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

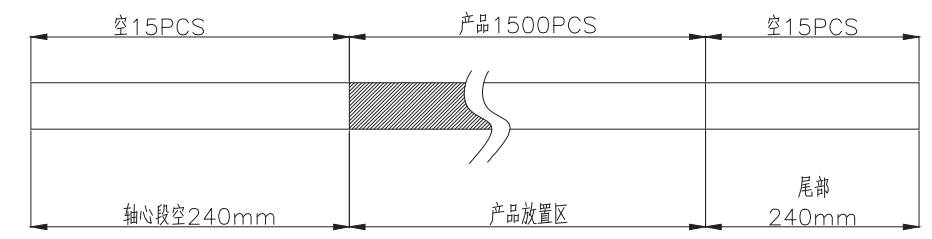
▨ PAD
▩ KEEP OUT AREA

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: NANO SIM CARD 1.37H PUSH PUSH 有桩	
		PAR	SMN-303S-ACP7
DECIMALS:		DWN	
ANGLES:		CHKD	
X.: ±0.35	X': ±2'	APVD	
.X: ±0.15	.X': ±1'	SCALE: 1:1	UNIT: MM
.XX: ±0.10	.XX': ±0.5'	SIZE: A4	SHEET: 1F1
CUSTOMER COPY			REV: A

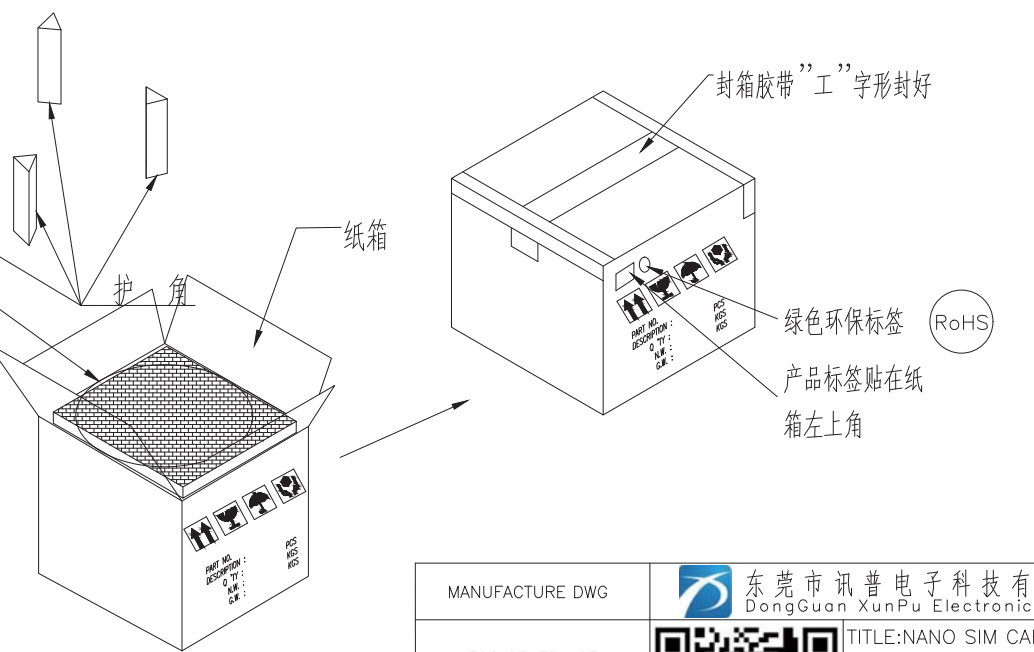
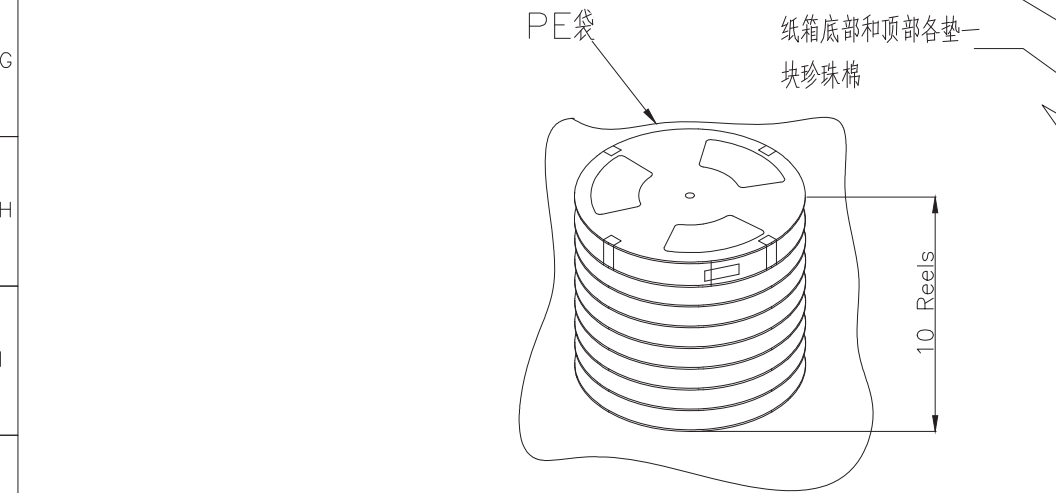


NOTES

1. 每卷包装数量: 1500PCS/每卷
2. 卷带包装方式:



3. 每箱包装数量: 15000PCS/箱
4. 纸箱 350mm*350mm*340mm (内部尺寸), 材质K=K



将10卷产品放入箱内

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES		TITLE: NANO SIM CARD 1.37H PUSH PUSH 有柱 包装图 PAR SMN-303S-ACP7	
DECIMALS:	ANGLES:	DWN	
X.: ±0.35	X': ±2°	CHKD	
.X: ±0.15	.X': ±1°	APVD	
.XX: ±0.10	.XX': ±0.5°	SCALE: 1:1	UNIT: MM
CUSTOMER COPY		SIZE: A4	SHEET: 2F2
			REV: A